



YEA SHIN TECHNOLOGY CO., LTD

YSE3908ZBB

N-Channel Enhancement MOSFET

VDS= 30V, ID= 48A



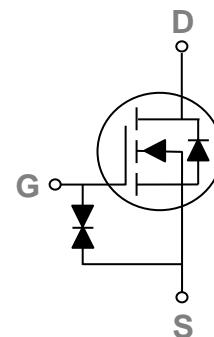
Features

- 30V, 48A, $R_{DS(ON)} = 8.5m\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- POL Buck Applications
- SMPS 2nd SR

PPAK3x3 Pin Configuration



Absolute Maximum Rating $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ C$)	48	A
	Drain Current – Continuous ($T_c=100^\circ C$)	30	A
I_{DM}	Drain Current – Pulsed ¹	192	A
EAS	Single Pulse Avalanche Energy ²	45	mJ
IAS	Single Pulse Avalanche Current ²	30	A
P_D	Power Dissipation ($T_c=25^\circ C$)	35	W
	Power Dissipation – Derate above $25^\circ C$	0.28	W/ $^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	3.6	$^\circ C/W$

DEVICE CHARACTERISTICS

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 10	μA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-source On-Resistance ³	$V_{\text{GS}}=10\text{V}$, $I_D=16\text{A}$	---	6.2	8.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=8\text{A}$	---	9	13	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
			---	-4	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=8\text{ A}$	---	9.5	---	S

Dynamic and Switching Characteristics

Q_g	Total Gate Charge ^{3,4}	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=20\text{A}$	---	7.5	12	nC
Q_{gs}	Gate-Source Charge ^{3,4}		---	1.3	2.6	
Q_{gd}	Gate-Drain Charge ^{3,4}		---	4.5	8	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3,4}	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$, $I_D=15\text{A}$	---	4.8	9	ns
T_r	Rise Time ^{3,4}		---	12.5	24	
$T_{\text{d(off)}}$	Turn-On Delay Time ^{3,4}		---	27.6	52	
T_f	Fall Time ^{3,4}		---	8.2	16	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	680	1000	pF
C_{oss}	Output Capacitance		---	150	220	
C_{rss}	Reverse Transfer Capacitance		---	70	105	
R_g	Gate Resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $f=1\text{MHz}$	---	2.7	5.4	Ω

Guaranteed Avalanche Energy

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{\text{DD}}=25\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=15\text{A}$	12			mJ

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	48	A
I_{SM}	Pulsed Source Current ³		---	---	192	A
V_{SD}	Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=30\text{A}$, $R_g=25\Omega$, Starting $T_J=25^\circ\text{C}$.
- The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.

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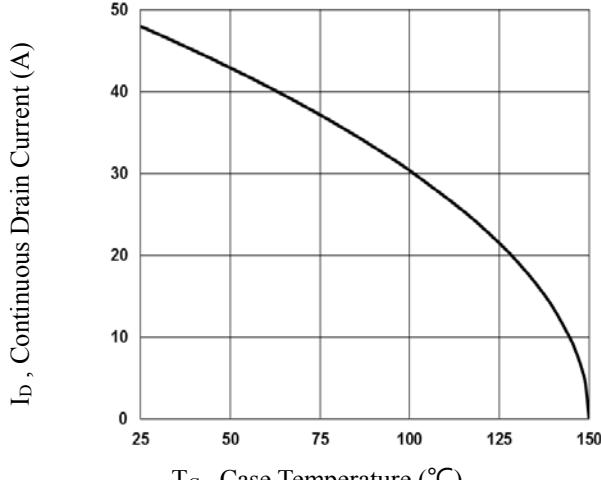


Fig.1 Continuous Drain Current vs. T_C

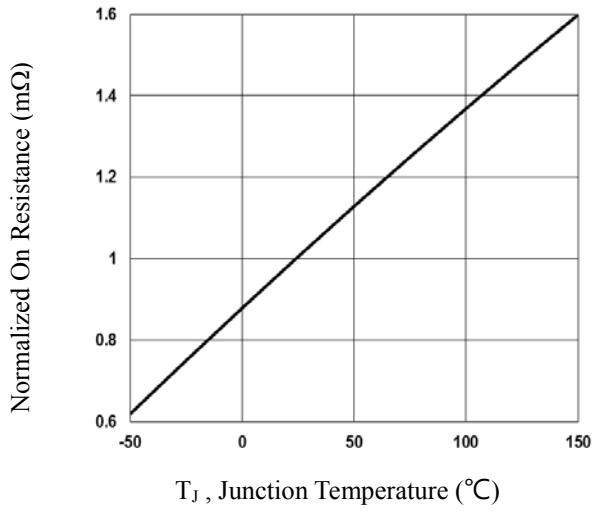


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

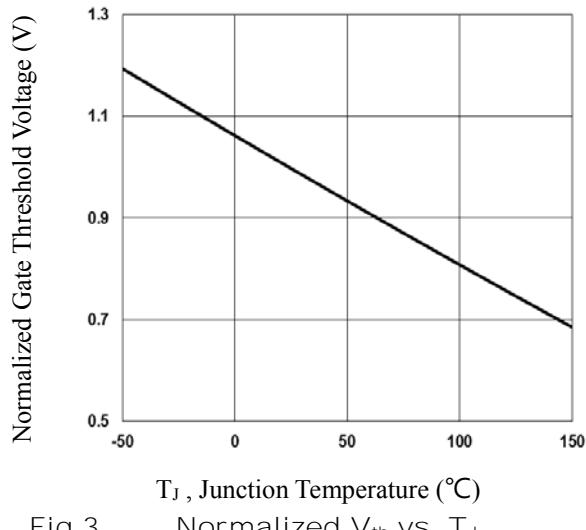


Fig.3 Normalized V_{th} vs. T_J

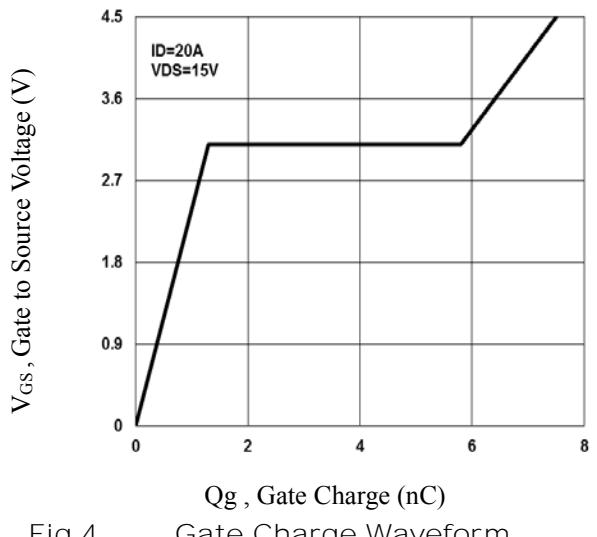


Fig.4 Gate Charge Waveform

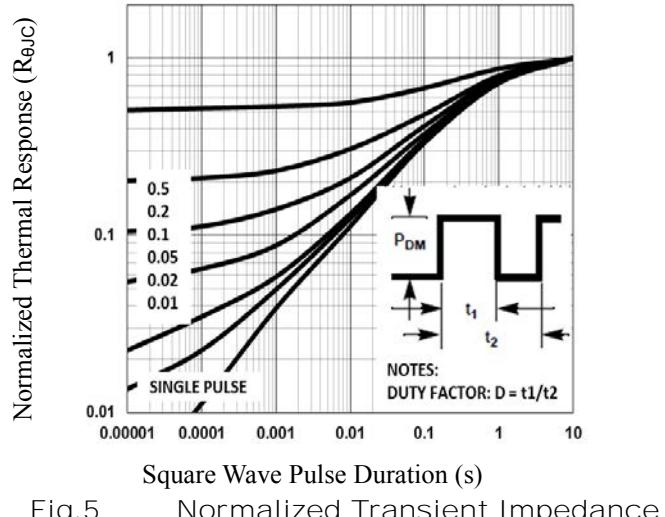


Fig.5 Normalized Transient Impedance

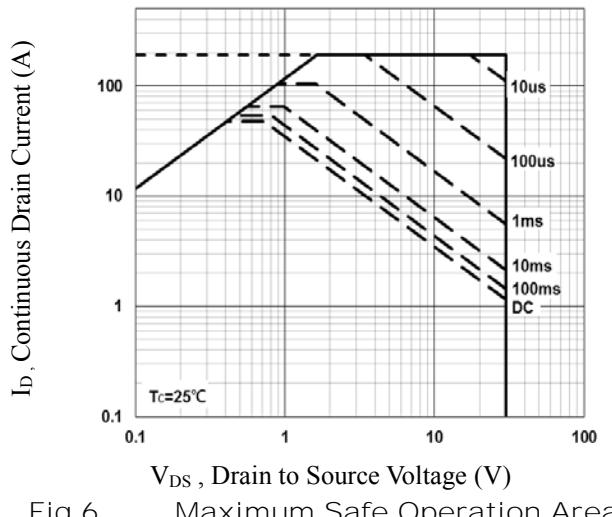


Fig.6 Maximum Safe Operation Area

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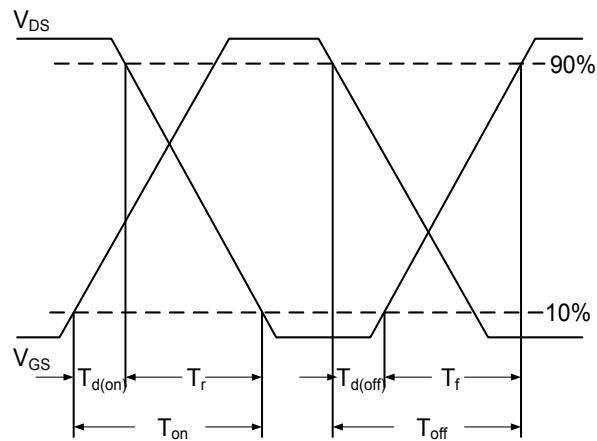


Fig.7 Switching Time Waveform

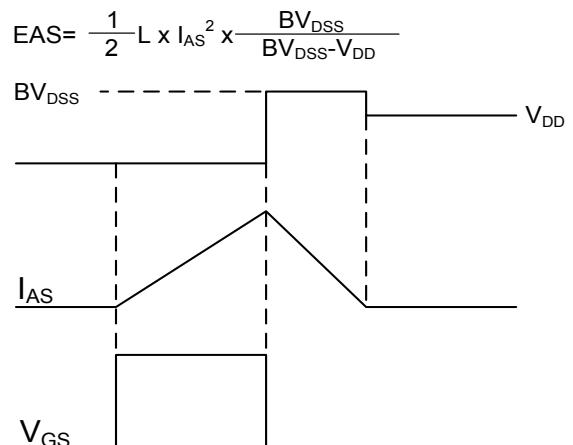
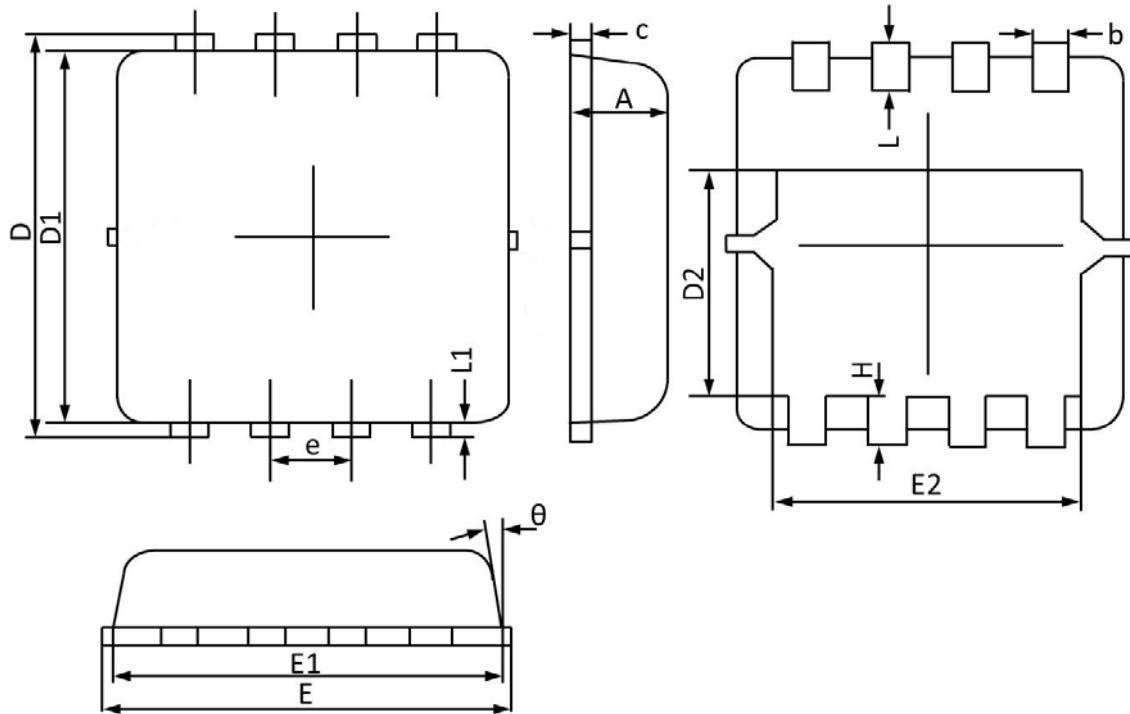


Fig.8 EAS Waveform

PACKAGE OUTLINE & DIMENSIONS

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PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.900	0.028	0.035
b	0.240	0.350	0.009	0.014
c	0.100	0.250	0.004	0.010
D	3.050	3.450	0.120	0.136
D1	2.900	3.200	0.114	0.126
D2	1.350	1.850	0.053	0.073
E	3.000	3.400	0.118	0.134
E1	2.900	3.250	0.114	0.128
E2	2.350	2.600	0.093	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.012	0.020
L	0.300	0.500	0.012	0.020
L1	0.200	0.700	0.003	0.008
θ	0°	12°	0°	12°